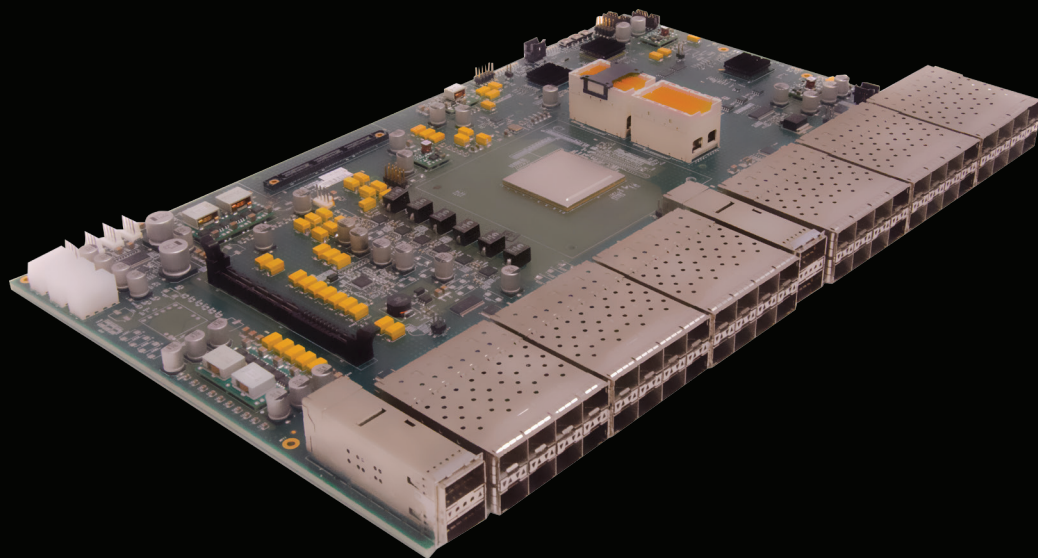




LEADERSHIP IN PRODUCT DESIGN AND NEW PRODUCT INTRODUCTION.

The Sanmina San Jose, California facility partners with some of the world's most innovative high-technology companies to design and prototype complex electronic and electro-mechanical products. We provide a full range of design and engineering services to companies in the communications and networking, computing and storage, medical, industrial, semi-conductor and clean technology sectors. The San Jose operation specializes in hardware design, system architecture, high-speed board and backplane design, mechanical, thermal, test engineering, DFM, design validation, reliability testing and failure analysis. We also provide comprehensive services for supply chain development, component engineering, process development and New Product Introduction (NPI). We manage all aspects of product engineering support during manufacturing, including cost-reduction, redesign when components become obsolete, sustaining engineering and documentation management. With years of product design and development experience, we provide comprehensive design services for a wide range of products and components while you retain all rights to product IP.

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ENGINEERING CAPABILITIES

- Turnkey or Subsystem Design and Engineering Services
- Integrated Project Team of Design, Process, Manufacturing and Test Engineers
- PCB and Backplane Design and Layout
- Design of Enclosures, Chassis, Cabinets, Racks
- High-Speed Design, Simulation, Analysis, Test and Measurements
- Software and Firmware Development
- Signal integrity, Thermal Analysis, Reliability Testing, and Failure Analysis of Components, Packages, Boards, and Sub-Systems
- NPI Engineering Support for Prototype Fabrication, Assembly, Test and Debug
- Test Development: End-to-End Strategy, In-Circuit, Functional, System Level
- Design Validation Testing
- Regulatory Certification Support
- Low-Cost Region Design Resources
- On-Site (Co-Location) of Design Resources at Customer Location

MANUFACTURING & TESTING CAPABILITIES

- Full-Service, Microelectronic Assembly and Test
- Complex Optical Assembly, including Specialty Fiber Splicing
- Experience with Complex Connectorization, Custom Packaging, Flex Circuit and Large Backplane Technologies
- Precision Automated SMT Assembly from 01005 to Flip Chip
- System-Level Integration, Box-Build and Test
- Value-Add/Value Engineering (VA/VE) Services
- Complex Backplane Manufacturing
- Cable Assemblies and Wire Harnesses
- Advanced Printed Circuit Boards